

Product/Process Change Notification

N° 2021-128-A

Dear customer,

please find attached our Infineon Technologies AG PCN:

Introduction of an additional wafer production and wafer test location at Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia for IGBT4A, and change of wafer diameter from 150 mm to 200 mm for EC4A diodes in 1200V modules

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2022-01-05.
- Infineon aligns with the widely-recognized JEDEC STANDARD “JESD46”, which stipulates: “Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”
Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress.

We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.

For further details, please visit our website:

<https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/>

Infineon Technologies AG

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Chairman of the Supervisory Board: Dr. Wolfgang Eder

Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Constanze Hufenbecher, Dr. Sven Schneider

Registered Office: Neubiberg

Commercial Register: München HRB 126492

Product/Process Change Notification

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Products affected

Please refer to attached affected product list 1_cip21128_A

Detailed change information

Subject: Introduction of an additional wafer production and wafer test location at Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia for IGBT4A, and change of wafer diameter from 150 mm to 200 mm for EC4A diodes in 1200V modules

Reason/Motivation: For IGBT4A, expansion of wafer production to assure continuity of supply and enable flexible manufacturing.
For EC4A, the 200 mm wafer manufacturing technology is the 'state of the art' wafer manufacturing technology at Infineon. Therefore, the diodes will be shifted from 150 mm wafer diameter to 200 mm wafer diameter.

Description	<u>Old</u>	<u>New</u>
PROCESS - WAFER PRODUCTION: New wafer diameter	Wafer diameter, EC4A: 150 mm	Wafer diameter, EC4A: 200 mm
PROCESS - WAFER PRODUCTION: Move all or parts of production to a different wafer fab site.	Wafer production and preassembly location, IGBT4A: Infineon Technologies Austria AG, Villach, Austria	Wafer production and preassembly location, IGBT4A: Infineon Technologies Austria AG, Villach, Austria and Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia
TEST FLOW: Move of all or part of electrical wafer test and/or final test to a different test site.	Wafer test location, IGBT4A: Infineon Technologies Austria AG, Villach, Austria	Wafer test location, IGBT4A: Infineon Technologies Austria AG, Villach, Austria and Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia

Product identification

Traceability assured via date code.
No change in SP ordering number.

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Anticipated impact of change Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability. No change in fit and form.
DeQuMa-ID(s): SEM-PW-02 / SEM-PW-13 / SEM-TF-01

Attachments

1_cip21128_A affected product list

Time schedule

Final qualification report	available
First samples available	on request
Intended start of delivery [1]	2022-03-01
Last order date (LOD) [2]	2021-11-30
Last delivery date (LDD) [3]	2022-04-30

[1] provided date or earlier after customer approval

[2] Last time buy volume to be placed latest until LOD

[3] Delivery of new product can be earlier (see Intended start of delivery) and depends on approval

If you have any questions, please do not hesitate to contact your local sales office.



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Sales name	SP number	OPN	Package
FS380R12A6T4B	SP001632438	FS380R12A6T4BBPSA1	AG-HYBRIDD-1-4
FS380R12A6T4LB	SP002516834	FS380R12A6T4LBBPSA1	AG-HYBRIDD-1-4